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12/31/03

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re issue application of:  
Rajiv Vasant Joshi

Application for Reissue of U.S. Patent 6,335,569

Title: Soft Metal Conductor and Method of Making

Free  
Joshi

PRELIMINARY AMENDMENT

Mail Stop Reissue  
Commissioner for Patents  
P.O. Box 1450  
Alexandria, VA 22313-1450

Sir:

Prior to the examination of the claims, please amend the application as follows:

In the Drawings:

Please amend Figure 6 as indicated in the attached sheet.

In the Claims:

Please introduce claims 17-37 as follows:

17. A semiconductor structure, comprising:

a plated multigrained soft metal conductor having a polished upper surface, said plated multigrained soft metal conductor containing at least some individual grains having a size of at least about 200 nm, wherein said soft metal conductor is formed over an underlying semiconductor layer, said underlying semiconductor layer having at least one semiconductor device therein.

18. The structure according to claim 17 wherein said semiconductor layer comprises

logic and memory devices on a single chip.

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01 FC:1201	344.00 DA
02 FC:1202	252.00 DA

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